

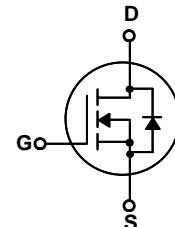
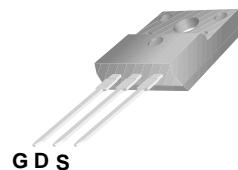

**Wisdom  
Technologies Int'l**

## WFF8N60

**600V N-Channel MOSFET**

### Features

- Low Intrinsic Capacitances
- Excellent Switching Characteristics
- Extended Safe Operating Area
- Unrivalled Gate Charge : $Q_g = 40\text{nC}$  (Typ.)
- $\text{BV}_DSS = 600\text{V}, \text{ID} = 7.5\text{A}$
- $R_{DS(on)} : 1.32 \Omega$  (Max) @  $\text{VG} = 10\text{V}$
- 100% Avalanche Tested


**TO-220F**
**G-Gate,D-Drain,S-Source**

### Absolute Maximum Ratings $T_c = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	WFF8N60	Units
$V_{DSS}$	Drain-Source Voltage	600	V
$I_D$	Drain Current -continuous ( $T_c = 25^\circ\text{C}$ )	7.5*	A
	-continuous ( $T_c = 100^\circ\text{C}$ )	4.7*	A
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Plused Avalanche Energy (Note1)	420	mJ
$I_{AR}$	Avalanche Current (Note2)	7.5	A
$P_D$	Power Dissipation ( $T_c = 25^\circ\text{C}$ )	48	W
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 ~ +150	$^\circ\text{C}$
TL	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max	Units
$R_{\theta JC}$	Thermal Resistance,Junction to Case	--	2.6	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance,Junction to Ambient	--	62.5	$^\circ\text{C}/\text{W}$

\* Drain current limited by maximum junction temperature.

**Electrical Characteristics**  $T_c=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Typ.	Max	Units
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$I_D=250 \mu\text{A}, V_{GS}=0$	600	--	--	V
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D=250 \mu\text{A}, \text{Reference to } 25^\circ\text{C}$	--	0.67	--	V/ $^\circ\text{C}$
IDSS	Zero Gate Voltage Drain Current	$V_{DS}=600\text{V}, V_{GS}=0\text{V}$	--	--	10	$\mu\text{A}$
		$V_{DS}=480\text{V}, T_c=125^\circ\text{C}$			100	$\mu\text{A}$
IGSSF	Gate-body leakage Current, Forward	$V_{GS}=+30\text{V}, V_{DS}=0\text{V}$	--	--	100	nA
IGSSR	Gate-body leakage Current, Reverse	$V_{GS}=-30\text{V}, V_{DS}=0\text{V}$	--	--	-100	nA

**On Characteristics**

$V_{GS(\text{th})}$	Date Threshold Voltage	$I_D=250\mu\text{A}, V_{DS}=V_{GS}$	2	--	4	V
$R_{DS(\text{on})}$	Static Drain-Source On-Resistance	$I_D=3.7\text{A}, V_{GS}=10\text{V}$	--	--	1.32	$\Omega$

**Dynamic Characteristics**

Ciss	Input Capacitance	VDS=25V, $V_{GS}=0$ , $f=1.0\text{MHz}$	--	1100	1430	pF
Coss	Output Capacitance		--	135	175	pF
Crss	Reverse Transfer Capacitance		--	16	21	pF

**Switching Characteristics**

Td(on)	Turn-On Delay Time	VDD=300V, $ID=7\text{A}$ RG=25 $\Omega$ (Note 3,4)	--	30	70	nS
Tr	Turn-On Rise Time		--	80	170	nS
Td(off)	Turn-Off Delay Time		--	65	140	nS
Tf	Turn-Off Fall Time		--	60	130	nS
Qg	Total Gate Charge	VDS=480, $V_{GS}=10\text{V}$ , $ID=7\text{A}$ (Note 3,4)	--	29	38	nC
	Gate-Source Charge		--	7	--	nC
	Gate-Drain Charge			14.5	--	nC

**Drain-Source Diode Characteristics and Maximum Ratings**

$I_S$	Maximum Continuous Drain-Source Diode Forward Current	--	--	7.5	A	
$I_{SM}$	Maximum Plused Drain-Source DiodeForward Current	--	--	28	A	
$V_{SD}$	Drain-Source Diode Forward Voltage	$I_D=7\text{A}$	--	--	1.5	V
trr	Reverse Recovery Time	$I_S=7\text{A}, V_{GS}=0\text{V}$	--	320	--	nS
Qrr	Reverse Recovery Charge	$dI_F/dt=100\text{A}/\mu\text{s}$ (Note3)	--	2.4	--	$\mu\text{C}$

\*Notes 1,  $L=15.7\text{mH}$ ,  $I_{AS}=7.5\text{A}$ ,  $VDD=50\text{V}$ ,  $RG=25\Omega$ , Starting  $TJ=25^\circ\text{C}$

2, Repetitive Rating : Pulse width limited by maximum junction temperature

3, Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$

4, Essentially Independent of Operating Temperature

## Typical Characteristics

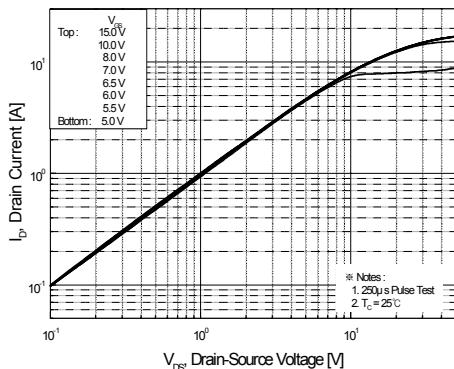


Figure 1. On-Region Characteristics

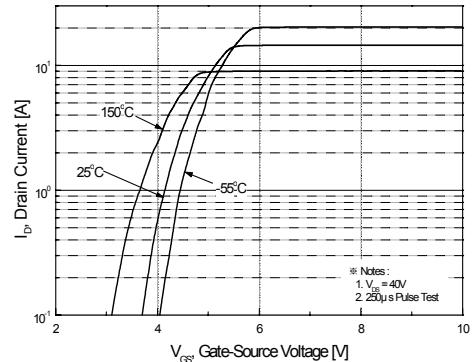


Figure 2. Transfer Characteristics

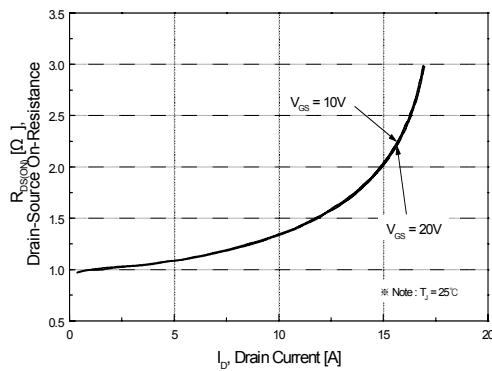


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

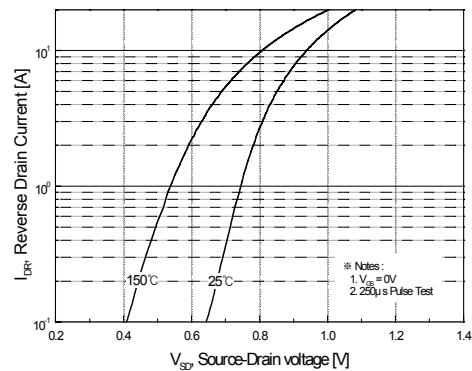


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

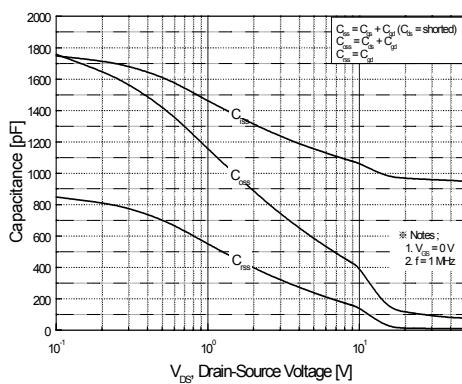


Figure 5. Capacitance Characteristics

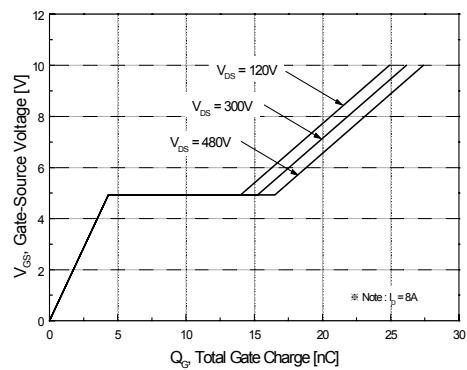
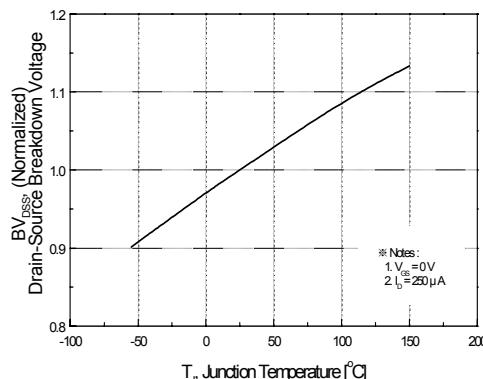
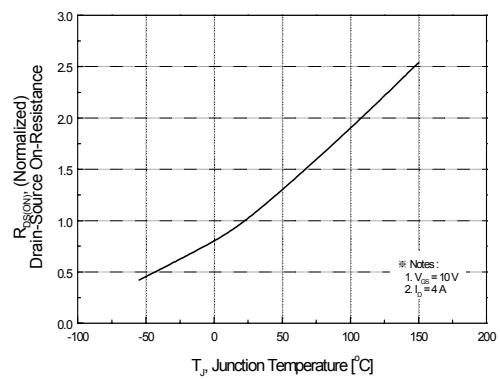


Figure 6. Gate Charge Characteristics

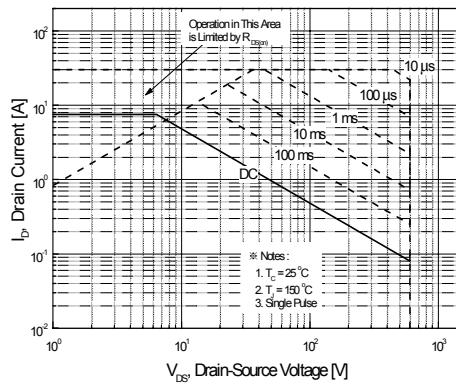
## Typical Characteristics (Continued)



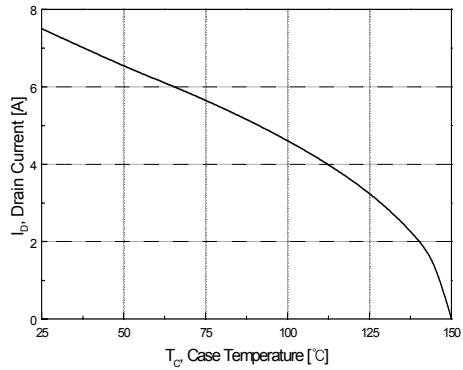
**Figure 7. Breakdown Voltage Variation  
vs Temperature**



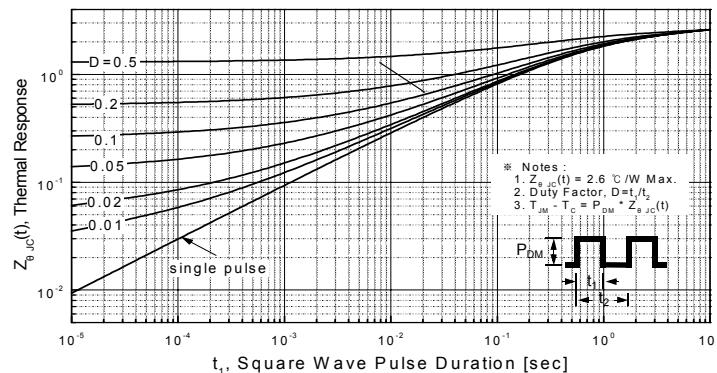
**Figure 8. On-Resistance Variation  
vs Temperature**



**Figure 9-2. Maximum Safe Operating Area  
for WFF8N60**

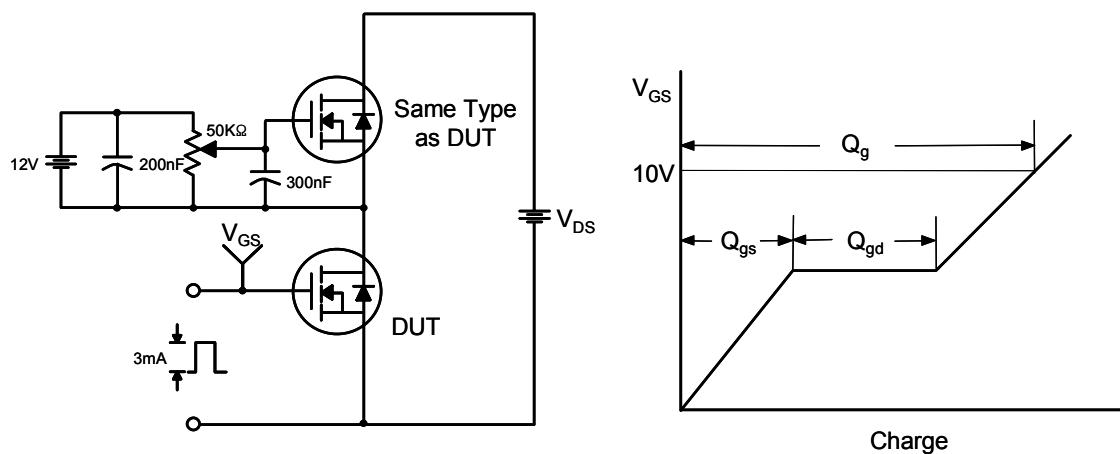


**Figure 10. Maximum Drain Current  
vs Case Temperature**

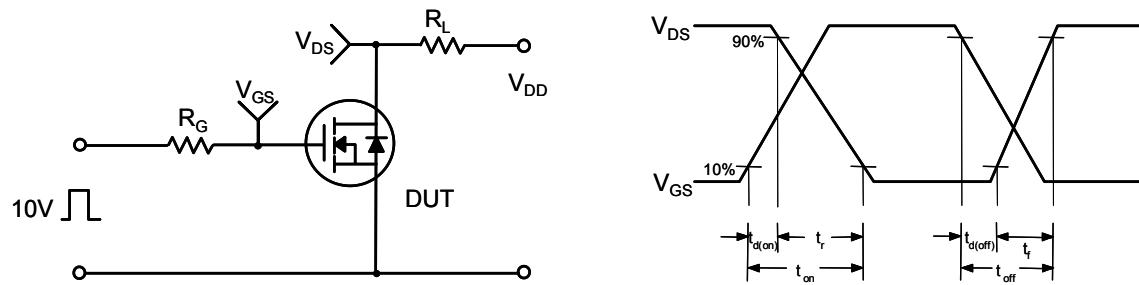


**Figure 11-2. Transient Thermal Response Curve for WFF8N60**

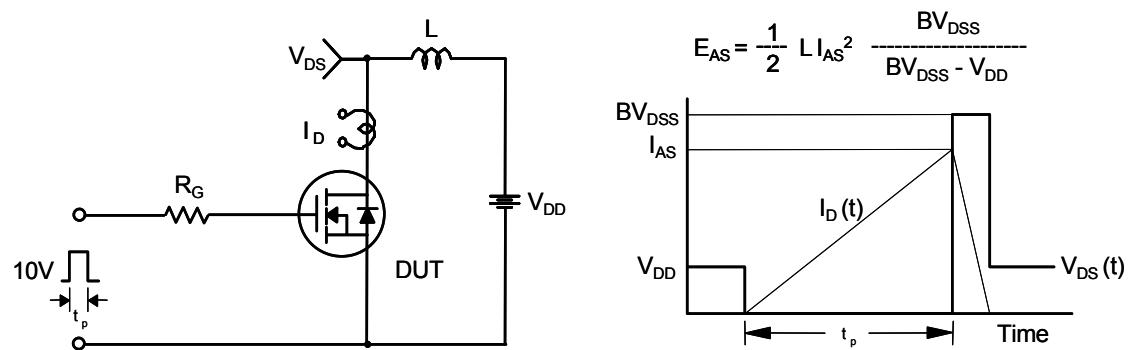
## Gate Charge Test Circuit &amp; Waveform



## Resistive Switching Test Circuit &amp; Waveforms



## Unclamped Inductive Switching Test Circuit &amp; Waveforms



**Peak Diode Recovery dv/dt Test Circuit & Waveforms**

